

Description

TH930 is a one-part thermal conductive interface material based on silicone resins. It is designed for very good thermal conduction with high electrical insulation.

Features

- High thermal conductivity
- High compressible
- Non electrical conductive

Applications

- Thermally conductive silicone based putty for use as thermal interface material for electronic component.
- Stencil printed TH930



Properties	Typical Value	Unit	Test Method	
Color	White	-	PEN 10	
Specific gravity	3.06	g/cm ³	PEN 14	
Viscosity	824,320	cP	PEN 144	
Thixotropic index	3.5	-	PEn 144	
Flow test, 45° incline	No flow	mm	PEN 15	
Extrusion rate				
1) At 50psi	0.11	g/min	PEN 107	
2) At 60psi	0.16	g/min	PEN 107	
3) At 80psi	0.22	g/min	PEN 107	
Minimum bond line thickness	0.08	mm	-	
Thermal conductivity	5.0	W/mK	ASTM D5470	
Thermal resistance	2.9	K.cm ² /W	ASTM D5470	
Volume resistivity	>1.0 x 10 ¹⁴	Ohm-cm	ASTM D257	
Volatile content @ 85°C	0.09	%	PEN 92	
Volatile content @ 150°C	0.39	%	PEN 92	
Bleed test, blot width	3.5	mm	PEN 99	
Operating temperature	-60 to 200	0°	PEN 92	

* The values above are tested based on batch to batch basis. These values are not used as a basis for preparing specifications.

* PEN is referring to Penchem's standard test method; ASTM is for test reference only.

* Viscosity and thixotropic index were measure by Rheometer, MCR72, PP25/s, 0.50mm gap, 1 and 10(1/s) shear rate, 25.0°C.

* Extrusion rate was measured by using needle size:GA15, 10ml EFD syringe, 25.0°C

* Oil bleed was measured at 1.00±0.05g on paper, 100°C/24hrs

Heat Aging (125°C) and Damp Heat Test (85°C, 85% RH) for 500hrs

Test condition	Parameter	Initial	24hrs	168hrs	500hrs
At 125°C	Weight loss (%)	0	0.33	0.34	0.37
At 85°C/85%RH	Weight loss (%)	0	0.25	0.24	0.24

Remark: Weight of the specimen = 0.50±0.01g

Guideline of Use

1) Wear rubber glove when handling the silicone putty.

- 2) Scoop a quantity of the silicone putty from the container using a stainless steel or plastic spatula.
- 3) Work and knead the putty around electronic part and circuit by hand.

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TH930 Silicone Thermal Putty

- 4) This product may be dispensed by pneumatic dispenser or other dispensing equipment with an appropriate needle. Increasing the dispensing temperature (eg. 60°C) can ease the dispensing process. The user is responsible to determine the suitability of the product for all intended uses.
- 5) Wipe off any excess putty with a piece of dry cloth. Further cleaning of residues may be achieved by wiping with cloth wetted with isopropanol.

Features

This product has 18 months of shelf life from date of manufacturing, unless otherwise specified, when stored at room temperature in the original and unopened container.

Applications

- 30ml syringe
- 500g plastic jar

Other packaging enquiry, please contact our sales department.

Environment, Health & Safety

This product is intended for industrial use only. For more safety information, please refer to Product Safety Data Sheet (SDS).

General Information

• All right reserved. This information in this document is subjected to change without notice.



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